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REMARKS/ARGUMENTS

Claims 92-129 and 151-164 are pending. Claims 94, 95, 98, 124 and 155 are withdrawn. Claims 1-91 and 130-150 are canceled.

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In regards to Claim 93, the subject matter that "said metal pillar comprises copper" leads that said metal pillar has good electrical conductivity.

10 In regards to Claim 97, the subject matter that "said metal pillar comprises an electroplated metal" leads said metal pillar to be easily formed with a great thickness.

In regards to Claims 98 and 99, the subject matter that "said tin-containing cap further comprises lead or bismuth" leads said tin-containing cap to be a good solder.

15 In regards to Claim 100, the subject matter that "said tin-containing cap further comprises an electroplated metal" leads said tin-containing cap to be easily formed with a great thickness.

20 In regards to Claim 104, the subject matter that "said tin-containing cap has a melting point lower than that of said metal pillar" leads that a great gap may exist between said semiconductor device and an external circuit.

25 In regards to Claims 106-116, the subject matter that "said metal layer comprises titanium, tungsten, chromium, copper, nickel, cobalt, silver, gold, tin, vanadium or palladium" leads said metal pillar to be firmly fixed or easily formed over said semiconductor device.

30 In regards to Claim 117, the subject matter that "said metal layer comprises a sputtered metal" leads said metal layer to be formed with a thin thickness.

In regards to Claim 119, the subject matter that "said metal pillar has a height greater than that of said tin-containing cap" leads that a great gap may exist between said semiconductor device and an external circuit.

5 In regards to Claims 123 and 125, the subject matter that "said metal layer comprises titanium or chromium" leads said copper pillar to be firmly fixed or easily formed over said semiconductor device.

10 In regards to Claims 124, the subject matter that "said tin-containing cap further comprises lead" leads said tin-containing cap to be a good solder.

15 In regards to Claims 126, the subject matter that "the semiconductor device further comprising a conductive layer between said copper pillar and said tin-containing cap, said copper pillar having a height greater than that of said conductive layer" leads said tin-containing cap to be firmly fixed or easily formed over said copper pillar.

20 In regards to Claim 129, the subject matter that "said tin-containing cap has a melting point lower than that of said metal pillar" leads that a great gap may exist between said semiconductor device and an external circuit.

In regards to Claim 151, the subject matter claimed in Claim 151 provides a way to bond said semiconductor device to an external circuit.

25 In regards to Claims 154, 156 and 157, the subject matter that "said metal layer comprises titanium, chromium and copper" leads said metal pillar to be firmly fixed or easily formed over said semiconductor device.

30 In regards to Claims 155 and 158, the subject matter that "said tin-containing cap further comprises lead or bismuth" leads said tin-containing cap to be a good solder.

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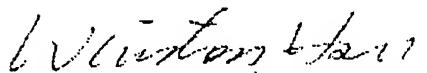
In regards to Claim 162, the subject matter that "said tin-containing cap has a melting point lower than that of said metal pillar" leads that a great gap may exist between said semiconductor device and an external circuit.

5 CONCLUSION

Some or all of the pending claims are believed to be in condition for allowance. Accordingly, allowance of the claims and the application as a whole are respectfully requested.

Applicant respectfully requests that a timely Notice of Allowance be issued in this  
10 case.

Sincerely yours,



Date: 03.08.2007

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